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Part Number: [0736441016](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position N/A, 144 Circuits

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)
[Test Summary \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73644](#)
Application Backplane
Comments Standard Press-Fit
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part Yes
Keying to Mating Part None
Material - Metal Phosphor Bronze, Stainless Steel
Material - Plating Mating Gold
Material - Plating Termination Gold
Material - Resin High Temperature Thermoplastic
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.138 In
PC Tail Length (mm) 3.50 mm
PCB Locator No
PCB Retention Yes
PCB Thickness Recommended (in) 0.098 In
PCB Thickness Recommended (mm) 2.50 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Pitch - Term. Interface (in) 0.079 In
Pitch - Term. Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 2
Plating min: Termination (µm) 0.05



Series

image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73644Series](#)

Mates With
[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

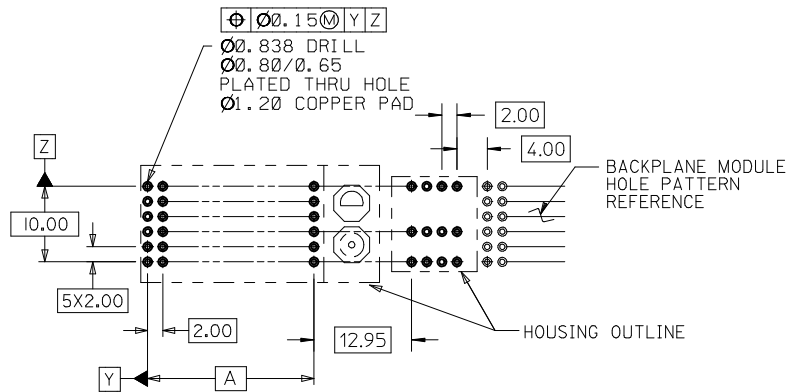
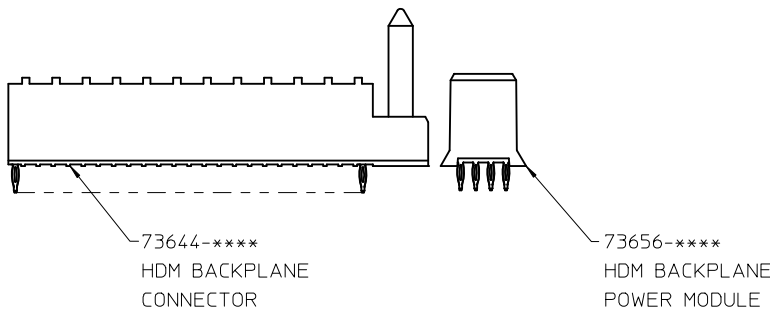
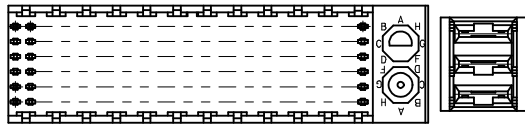
Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.
Global

Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
HDM® Backplane	0622005703
Insertion Head for	
144 Positions	

Polarized to PCB	No	Extraction Tool	0621001000
Stackable	No		
Surface Mount Compatible (SMC)	Yes		
Temperature Range - Operating	-55°C to +105°C		
Termination Interface: Style	Through Hole - Compliant Pin		
Electrical			
Current - Maximum per Contact	1A		
Data Rate	1.0 Gbps		
Real Signals (per 25mm)	75		
Shielded	No		
Voltage - Maximum	250V AC		
Material Info			
Reference - Drawing Numbers			
Packaging Specification	PK-70873-0818		
Sales Drawing	SD-73644-004, SDA-73644-****		
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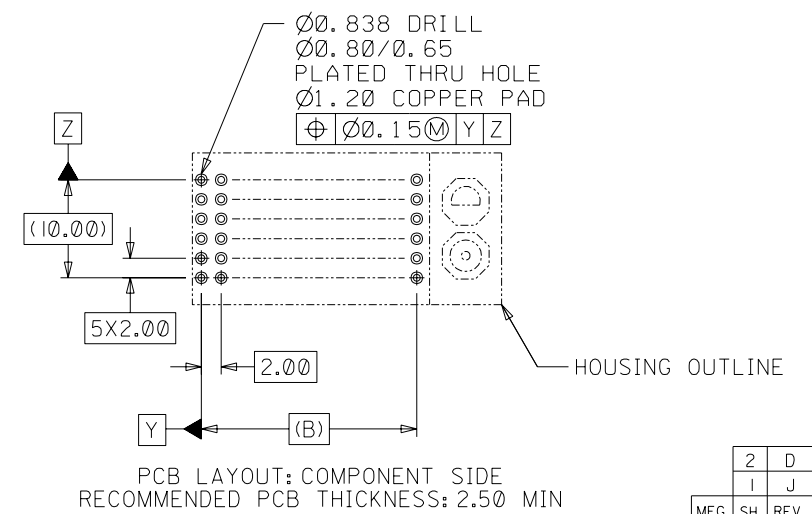
PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

- NOTES:
1. SEE SD-73644-**** FOR ADDITIONAL INFORMATION FOR THE 73644 BACKPLANE MODULE.
 2. SEE SD-73656-*00* FOR ADDITIONAL INFORMATION FOR THE 73656 MODULE.

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	DIM "A"
73644-00**	72	22.00
73644-01**	72	22.00
73644-02**	72	22.00
73644-10**	144	46.00
73644-11**	144	46.00
73644-12**	144	46.00
73644-20**	72	22.00
73644-21**	72	22.00
73644-22**	72	22.00
73644-30**	144	46.00
73644-31**	144	46.00
73644-32**	144	46.00

INITIAL RELEASE EC NO: UCP2009-3131 DRWN:SDANNELLEY 2009/08/05 CHKD:BSMART 2009/08/06 APPR:SMILLER 2009/08/07	REV A	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	TITLE PCB LAYOUT FOR 73644 AND 73659 CONNECTORS USED IN CONJUNCTION MOLEX INCORPORATED	
						DRAWN BY DATE SDANNELLEY 2009/06/26						
						CHECKED BY DATE BSMART 2009/06/26						
						APPROVED BY DATE SMILLER 2009/06/26						
						MATERIAL NO. N/A		DOCUMENT NO. SD-73644-004		SHEET NO. 1 OF 1		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

73644	4	3	2	73644
1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE. 2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MIN. THICKNESS; SELECTIVE TIN/LEAD (Sb/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.				



				I	REVISED ECR UDT2000-0348 BINGHAM 99/10/12	DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR $\pm 1/2^\circ$		$\nabla = 0$ $\blacktriangledown = 0$ REVISE ONLY ON CAD SYSTEM	
				H	REVISED ECR UDT1999-0662 BINGHAM 99/05/18	INCH METRIC 3 PLACE $\pm$ N/A --- 2 PLACE $\pm$ N/A ± 0.05 1 PLACE --- ± 0.10		TITLE SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION	
J REVISED ECR UCP2003-2260 THOMAS 03/04/25				G	REVISED ECR UDT1999-0476 BINGHAM 98/12/21	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX MOLEX INCORPORATED SHEET NO. DATE LISLE, ILL. 60532 U.S.A. 1 OF 2 96/12/18	
LTR. REVISIONS				LTR. REVISIONS	DRWG. BY JRR CHK'D. BY SMR APP'D. BY CAB SCALE 2 : 1		PART NO. DRWG. NO. SEE CHART SDA-73644-*****		
						FILE NAME S73644X1.DGN		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	
								DIV. SIZE DA B	

Данный компонент на территории Российской Федерации

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<http://moschip.ru/get-element>

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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